

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5401360

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MARC ANTHONY ISCHE	02/07/2014
AHMAD HATAMI	02/06/2014
ARDALAN HESHMATI	01/31/2014
ZOLTAN F. BIACS	01/29/2014
DOUGLAS N. ROWITCH	02/05/2013
DOMINIC FARMER	01/28/2014
SRIGOURI KAMARSU	02/06/2014
JIE WU	02/13/2013
RECEIVING PARTY DATA	
Name:	QUALCOMM Incorporated
Street Address:	5775 Morehouse Drive
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16191271
CORRESPONDENCE DATA	
Fax Number:	(858)658-2502
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	us-docketing@qualcomm.com
Correspondent Name:	QUALCOMM INCORPORATED
Address Line 1:	5775 MOREHOUSE DRIVE
Address Line 4:	SAN DIEGO, CALIFORNIA 92121
ATTORNEY DOCKET NUMBER:	081454D1C1C1C1
NAME OF SUBMITTER:	DULCIE FONTT
SIGNATURE:	/Dulcie Fontt/
DATE SIGNED:	03/01/2019

Total Attachments: 28

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2720882

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MARC ANTHONY ISCHE	02/07/2014
AHMAD HATAMI	02/06/2014
ARDALAN HESHMATI	01/31/2014
ZOLTAN F. BIACS	01/29/2014
DOUGLAS N. ROWITCH	02/05/2013
DOMINIC FARMER	01/28/2014
SRIGOURI KAMARSU	02/06/2014
JIE WU	02/13/2013

RECEIVING PARTY DATA

Name:	QUALCOMM Incorporated
Street Address:	5775 Morehouse Drive
Internal Address:	Patent Department/Central Administration
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121

PROPERTY NUMBERS Total: 3

Property Type	Number
Application Number:	13750851
Application Number:	12792678
Application Number:	61184410

CORRESPONDENCE DATA

Fax Number: (858)658-2502
 Phone: 858-845-4265
 Email: us-docketing@qualcomm.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name: QUALCOMM INCORPORATED
Address Line 1: 5775 MOREHOUSE DR.
Address Line 4: SAN DIEGO, CALIFORNIA 92121

ATTORNEY DOCKET NUMBER: 081454D1

NAME OF SUBMITTER: JOSEPH SALAZAR

Signature: /JOSEPH SALAZAR/

Date: 02/10/2014

Total Attachments: 24

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ASSIGNMENT

WHEREAS, WE,

1. **Marc Anthony ISCHE**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Diego, CA,
2. **Ahmad HATAMI**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Pleasanton, CA,
3. **Ardalan HESHMATI**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Saratoga, CA,
4. **Zoltan F. BIACS**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Mateo, CA,
5. **Douglas N. ROWITCH**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Honolulu, Hawaii,
6. **Dominic FARMER**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Los Gatos, CA,
7. **Srigouri KAMARSU**, a citizen of Canada, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Cupertino, CA,
8. **Jie WU**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **ON DEMAND POSITIONING** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/750,851 filed January 25, 2013, Qualcomm Reference No. 081454D1, and all provisional applications relating thereto, together with U.S. Application No(s). 12/792,678, filed February 10, 2013, Qualcomm Reference No. 081454, together with U.S. Provisional Application No(s). 61/184,410, filed June 5, 2009, Qualcomm Reference No. 081454P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, on 2/7/14
LOCATION DATE


Marc Anthony ISCHE

Done at _____, on _____
LOCATION DATE

Ahmad HATAMI

Done at _____, on _____
LOCATION DATE

Ardalan HESHMATI

Done at _____, on _____
LOCATION DATE

Zoltan F. BIACS

Done at _____, on _____
LOCATION DATE

Douglas N. ROWITCH

Done at _____, on _____
LOCATION DATE

Dominic FARMER

Done at _____, on _____
LOCATION DATE

Srigouri KAMARSU

Done at _____, on _____
LOCATION DATE

Jie WU

ASSIGNMENT

WHEREAS, WE,

1. **Marc Anthony ISCHE**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Diego, CA,
2. **Ahmad HATAMI**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Pleasanton, CA,
3. **Ardalan HESHMATI**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Saratoga, CA,
4. **Zoltan F. BIACS**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Mateo, CA,
5. **Douglas N. ROWITCH**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Honolulu, Hawaii,
6. **Dominic FARMER**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Los Gatos, CA,
7. **Srigouri KAMARSU**, a citizen of Canada, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Cupertino, CA,
8. **Jie WU**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **ON DEMAND POSITIONING** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **13/750,851** filed **January 25, 2013**, Qualcomm Reference No. **081454D1**, and all provisional applications relating thereto, together with U.S. Application No(s). **12/792,678**, filed **February 10, 2013**, Qualcomm Reference No. **081454**, together with U.S. Provisional Application No(s). **61/184,410**, filed **June 5, 2009**, Qualcomm Reference No. **081454P1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE

Marc Anthony ISCHE

Done at Santa Clara, on 2/6/2014
LOCATION DATE

A. HATAMI
Ahmad HATAMI

Done at _____, on _____
LOCATION DATE

Ardalan HESHMATI

Done at _____, on _____
LOCATION DATE

Zoltan F. BIACS

Done at _____, on _____
LOCATION DATE

Douglas N. ROWITCH

Done at _____, on _____
LOCATION DATE

Dominic FARMER

Done at _____, on _____
LOCATION DATE

Srigouri KAMARSU

Done at _____, on _____
LOCATION DATE

Jie WU

ASSIGNMENT

WHEREAS, WE,

1. **Marc Anthony ISCHE**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Diego, CA,
2. **Ahmad HATAMI**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Pleasanton, CA,
3. **Ardalan HESHMATI**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Saratoga, CA,
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7. **Srigouri KAMARSU**, a citizen of Canada, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Cupertino, CA,
8. **Jie WU**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **ON DEMAND POSITIONING** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/750,851 filed January 25, 2013, Qualcomm Reference No. 081454D1, and all provisional applications relating thereto, together with U.S. Application No(s). 12/792,678, filed February 10, 2013, Qualcomm Reference No. 081454, together with U.S. Provisional Application No(s). 61/184,410, filed June 5, 2009, Qualcomm Reference No. 081454P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE
Marc Anthony ISCHE

Done at _____, on _____
LOCATION DATE
Ahmad HATAMI

Done at SARASOTA, CA, on 1-31-14
LOCATION DATE

Ardalan HESHMATI

Done at _____, on _____
LOCATION DATE
Zoltan F. BIACS

Done at _____, on _____
LOCATION DATE
Douglas N. ROWITCH

Done at _____, on _____
LOCATION DATE
Dominic FARMER

Done at _____, on _____
LOCATION DATE
Srigouri KAMARSU

Done at _____, on _____
LOCATION DATE
Jie WU

ASSIGNMENT

WHEREAS, WE,

1. **Marc Anthony ISCHE**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Diego, CA,
2. **Ahmad HATAMI**, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of Pleasanton, CA,
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8. **Jie WU**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121, and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **ON DEMAND POSITIONING** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

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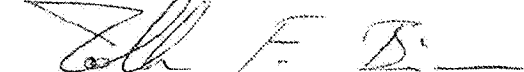
AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE
Marc Anthony ISCHE

Done at _____, on _____
LOCATION DATE
Ahmad HATAMI

Done at _____, on _____
LOCATION DATE
Ardalan HESHMATI

Done at San Jose, CA, on 1/29/2014²⁵
LOCATION DATE

Zoltan F. BIACS

Done at _____, on _____
LOCATION DATE
Douglas N. ROWITCH

Done at _____, on _____
LOCATION DATE
Dominic FARMER

Done at _____, on _____
LOCATION DATE
Srigouri KAMARSU

Done at _____, on _____
LOCATION DATE
Jie WU

ASSIGNMENT

WHEREAS, WE,

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Done at _____, on _____
LOCATION DATE Marc Anthony ISCHE

Done at _____, on _____
LOCATION DATE Ahmad HATAMI

Done at _____, on _____
LOCATION DATE Ardalan HESHMATI

Done at _____, on _____
LOCATION DATE Zoltan F. BIACS

Done at _____, on _____
LOCATION DATE Douglas N. ROWITCH

Done at _____, on _____
LOCATION DATE Dominic FARMER

Done at Santa Clara, on 2/6/14
LOCATION DATE K-Lin Gomi
Srigouri KAMARSU

Done at _____, on _____
LOCATION DATE Jie WU

ASSIGNMENT

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